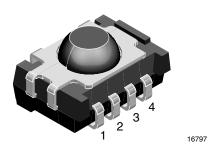


**Vishay Semiconductors** 

## **IR Receiver Modules for 3D Synchronization Signals**



### **MECHANICAL DATA**

**Pinning:** 1 = GND, 2 = N.C., 3 = V<sub>S</sub>, 4 = OUT

## FEATURES

• Center frequency at 25 kHz to reduce interference with IR remote control signals at 30 kHz to 56 kHz



RoHS

COMPLIANT

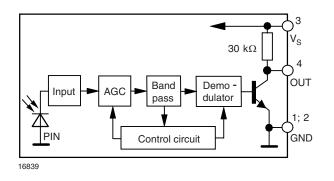
- Package can be used with IR emitters with wavelength 830 nm as well as standard 940 nm
- Very low supply current and stand-by mode
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Supply voltage range: 2.5 V to 5.5 V
- Improved immunity against modulated light sources
- Insensitive to supply voltage ripple and noise
- Taping available for topview and sideview assembly
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

### DESCRIPTION

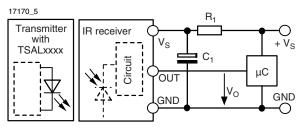
The TSOP35D25 is an SMD IR receiver module for 3D sychronisation signals. The receiver is designed to operate at a carrier frequency of 25 kHz and a wavelength of 830 nm to avoid interference with standard remote control systems at 940 nm and 30 kHz to 56 kHz. The TSOP35D25 can receive continuously transmitted signal patterns with a minimum burst length of 6 cycles and frame rates up to 200 Hz. The circuit provides good suppression of optical noise from CFLs, LCD backlight and plasma panels.

PARTS TABLE	
CARRIER FREQUENCY	GOOD NOISE SUPPRESSION AND FAST BURST RATE
25 kHz	TSOP35D25

### **BLOCK DIAGRAM**



#### **APPLICATION CIRCUIT**



 $R_1$  and  $C_1$  are recommended for protection against EOS. Components should be in the range of 33  $\Omega$  <  $R_1$  < 1 k $\Omega$ ,  $C_1$  > 0.1  $\mu F.$ 

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# IR Receiver Modules for 3D Synchronization Signals



ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
Supply voltage (pin 3)		V <sub>S</sub>	- 0.3 to + 6	V		
Supply current (pin 3)		ا <sub>S</sub>	3	mA		
Output voltage (pin 4)		Vo	- 0.3 to (V <sub>S</sub> + 0.3)	V		
Output current (pin 4)		Ι <sub>Ο</sub>	5	mA		
Junction temperature		Тj	100	°C		
Storage temperature range		T <sub>stg</sub>	- 40 to + 100	°C		
Operating temperature range		T <sub>amb</sub>	- 30 to + 85	°C		
Power consumption	$T_{amb} \le 85 \ ^{\circ}C$	P <sub>tot</sub>	10	mW		

#### Note

(1) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability.

ELECTRICAL AND OPTICAL CHARACTERISTICS <sup>(1)</sup> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Quarthy automatic (alia Q)	$E_v = 0, V_S = 3.3 V$	I <sub>SD</sub>	0.27	0.35	0.45	mA
Supply current (pin 3)	E <sub>v</sub> = 40 klx, sunlight	I <sub>SH</sub>		0.45		mA
Supply voltage		Vs	2.5		5.5	V
Transmission distance	$E_v = 0$ , test signal see fig. 1, IR diode TSAL6200, $I_F = 250 \text{ mA}$	d		45		m
Output voltage low (pin 4)	$I_{OSL} = 0.5 \text{ mA}, E_e = 0.7 \text{ mW/m}^2,$ test signal see fig. 1	V <sub>OSL</sub>			100	mV
Minimum irradiance	Pulse width tolerance: t <sub>pi</sub> - 80 µs < t <sub>po</sub> < t <sub>pi</sub> + 160 µs, test signal see fig. 1	E <sub>e min.</sub>		0.15	0.35	mW/m <sup>2</sup>
Maximum irradiance	$\begin{array}{c} t_{pi} \text{ - 80 } \mu s < t_{po} < t_{pi} \text{ + 160 } \mu s, \\ \text{test signal see fig. 1} \end{array}$	E <sub>e max.</sub>	30			W/m <sup>2</sup>
Directivity	Angle of half transmission distance	φ1/2		± 50		deg

## TYPICAL CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

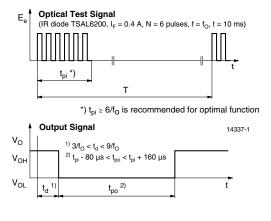


Fig. 1 - Output Active Low

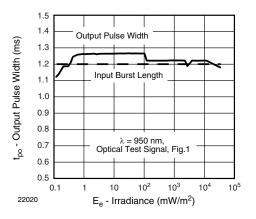
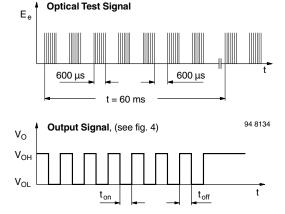


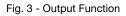
Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

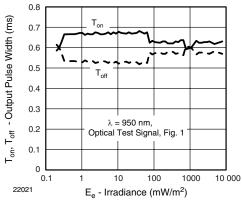


## **IR Receiver Modules for 3D** Synchronization Signals

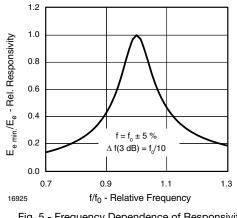
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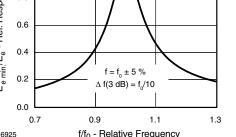














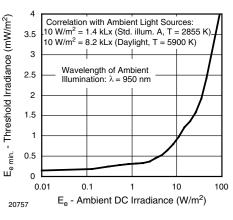
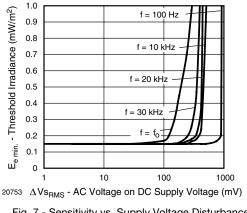
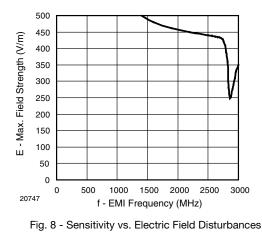


Fig. 6 - Sensitivity in Bright Ambient







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IR Receiver Modules for 3D Synchronization Signals



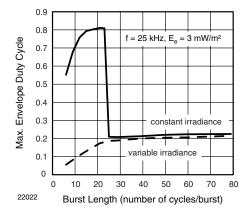


Fig. 9 - Maximum Envelope Duty Cycle vs. Burst Length

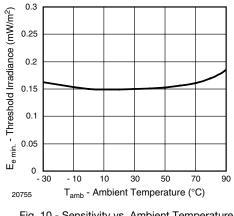
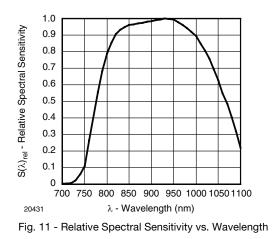
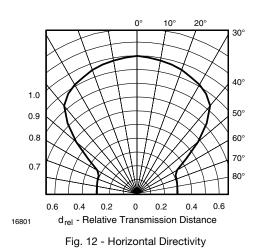
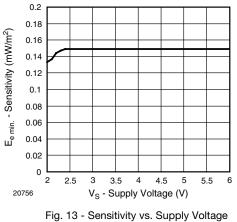


Fig. 10 - Sensitivity vs. Ambient Temperature







ig. to constituty vs. cupply voltage



IR Receiver Modules for 3D Synchronization Signals

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## SUITABLE DATA FORMAT

The TSOP35D25 is designed to suppress spurious output pulses due to noise or disturbance signals. Data and disturbance signals can be distinguished by the devices according to carrier frequency, burst length and envelope duty cycle. The data signal should be close to the band-pass center frequency (e.g. 25 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the TSOP35D25 in the presence of a disturbance signal, the sensitivity of the receiver is reduced to insure that no spurious pulses are present at the output. Some examples of disturbance signals which are suppressed are

- DC light (e.g. from tungsten bulb or sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated noise from fluorescent lamps with electronic ballasts (see figure 14 or figure 15)

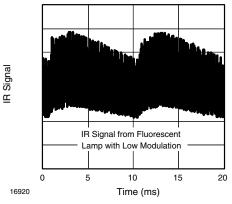


Fig. 14 - IR Signal from Fluorescent Lamp with Low Modulation

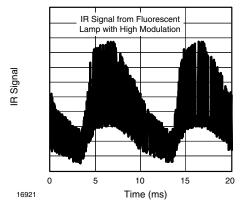


Fig. 15 - IR Signal from Fluorescent Lamp with High Modulation

	TSOP35D25
Minimum burst length	6 cycles/burst
After each burst of length a minimum gap time is required of	6 to 24 cycles ≥ 6 cycles
For bursts greater than a minimum gap time in the data stream is needed of	24 cycles > 4 x burst length
Maximum rate of short bursts (constant irradiance)	2000 bursts/s
Maximum rate of short bursts (variable irradiance)	220 bursts/s



IR Receiver Modules for 3D Synchronization Signals



### STAND-BY MODE OF THE TSOP35D25

If an application requires an ultra low average supply current in order to save battery life, the TSOP35D25 can be operated with an intermittent supply voltage. A typical application circuit shown in fig. 16.

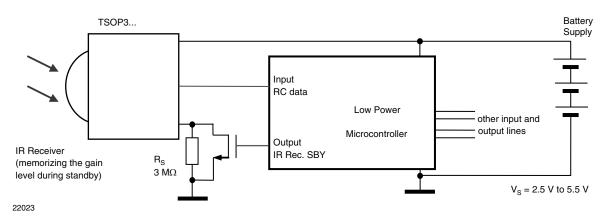


Fig. 16 - Application Circuit for the TSOP3...with Intermittent Supply Voltage

To receive a continuous data signal while using the TSOP3... with an intermittent supply voltage, the receiver must be activated in advance of the expected data frame as shown in figure 17.

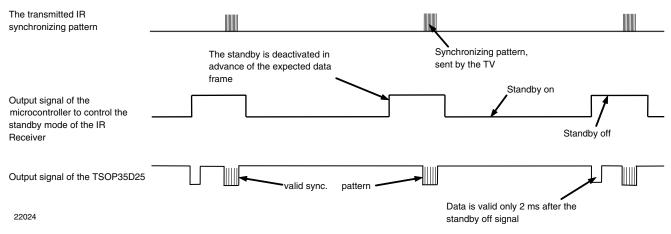


Fig. 17 - Signal Timing in Power Saving Mode with Continuous Receiving Function

In normal operation without using the stand-by feature, the gain level of the TSOP35D25 returns to a default level after the device is disconnected from supply voltage and reconnected again. A settling time of up to 100 ms is necessary until the gain has settled to an optimum level that is well matched to the ambient noise level.

Using the device in stand-by mode, the TSOP35D25 memorizes its gain setting while in standby. On re-activation, the gain immediately returns to the correct level present before stand-by. This operation insures that there are no spurious pulses on power-up due to mismatch between the gain level and the ambient light conditions.



## IR Receiver Modules for 3D Synchronization Signals

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<b>ELECTRICAL AND OPTICAL CHARACTERISTICS</b> <sup>(1)</sup> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Serial resistor to activate the	V <sub>S</sub> = 3 V	R <sub>S</sub>	1.2	1.5	2	MΩ
standby mode	V <sub>S</sub> = 5 V	R <sub>S</sub>	2	3	4	1015.2
Standby supply current	$V_S = 3 V, RS = 1.5 M\Omega$	I <sub>SBY</sub>	1	1.4	2	
Standby supply current	$V_{S} = 5 V, RS = 3 M\Omega$	I <sub>SBY</sub>	1	1.4	2	μA
Latency time for standby-off (delay until there is a valid respose)	V <sub>S</sub> > 2.5 V, dark ambient, output is valid	t <sub>delay</sub>		0.4	0.8	ms
	V <sub>S</sub> > 2.5 V, 10 kLux dayligth, output is valid	t <sub>delay</sub>		1.5	2.5	
Duration of standby-off period	V <sub>S</sub> > 2.5 V, dark ambient	t <sub>SBY_OFF</sub>	1			
	V <sub>S</sub> > 2.5 V, 10 kLux daylight, AGC1 or AGC3 device	t <sub>SBY_OFF</sub>	4			ms
	V <sub>S</sub> > 2.5 V, 10 kLux daylight, AGC2 or AGC4 device	t <sub>SBY_OFF</sub>	3			

## **TYPICAL CHARACTERISTICS** ( $T_{amb} = 25 \text{ °C}$ , unless otherwise specified)

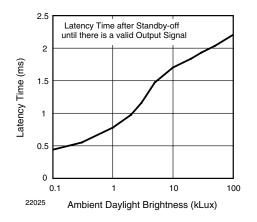


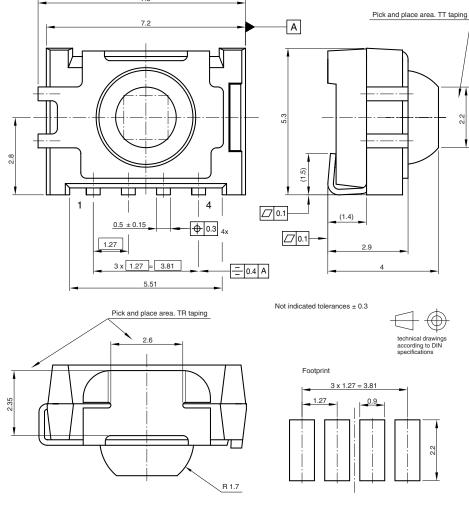
Fig. 1 - Delay Time after Standby-off until the TSOP3... is ready to receive Data

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IR Receiver Modules for 3D Synchronization Signals



### **PACKAGE DIMENSIONS** in millimeters



Drawing-No.: 6.544-5341.01-4 Issue: 8; 02.09.09

### **ASSEMBLY INSTRUCTIONS**

#### **Reflow Soldering**

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Excercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

#### Manual Soldering

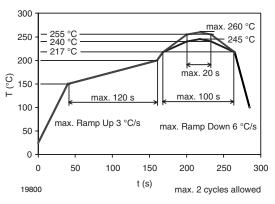
- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300  $^\circ\text{C}$
- Finish soldering within 3 s
- · Handle products only after the temperature has cooled off

## IR Receiver Modules for 3D Synchronization Signals

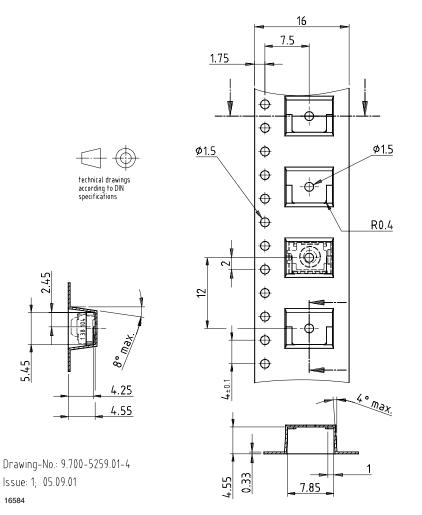
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**TSOP35D25** 

## VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



### TAPING VERSION TSOP..TT Dimensions in millimeters

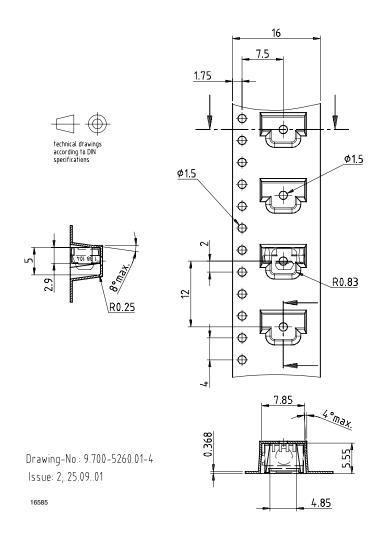


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IR Receiver Modules for 3D Synchronization Signals



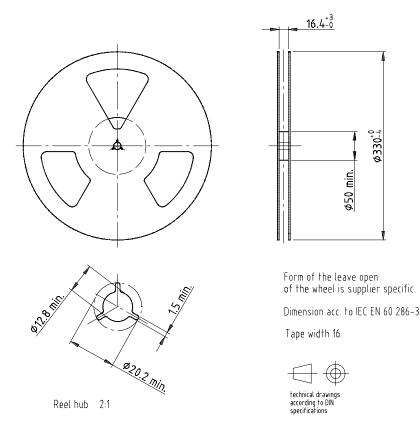
## TAPING VERSION TSOP..TR Dimensions in millimeters





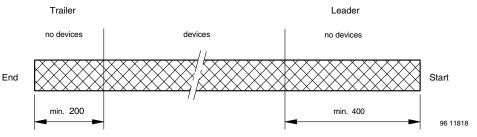
IR Receiver Modules for 3D Synchronization Signals **Vishay Semiconductors** 

#### **REEL DIMENSIONS** in millimeters



Drawing refers to following types: Reel for blister carrier tape Version B Drawing-No.: 9.800-5052.V2-4 Issue: 1; 07.05.02

#### LEADER AND TRAILER Dimensions in millimeters



#### **COVER TAPE PEEL STRENGTH**

According to DIN EN 60286-3 0.1 N to 1.3 N 300 mm/min. ± 10 mm/min. 165° to 180° peel angle

#### LABEL

#### Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

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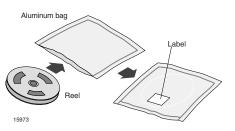
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PLAIN WRITTING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	XXXXXX+	Company logo
LONG BAR CODE TOP	ТҮРЕ	LENGTH
Item-number	Ν	8
Plant-code	Ν	2
Sequence-number	Х	3
Quantity	Ν	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	Ν	3
Batch-number	Х	10
Filter	-	1
Total length	-	17

## **DRY PACKING**

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



## **FINAL PACKING**

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

### **RECOMMENDED METHOD OF STORAGE**

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity  $\leq$  60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition: 192 h at 40 °C + 5 °C/- 0 °C and < 5 % RH (dry air/nitrogen) or

96 h at 60  $^\circ\text{C}$  + 5  $^\circ\text{C}$  and < 5 % RH for all device containers or

24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC standard JESD22-A112 level 4 label is included on all dry bags.

<ol> <li>Shelf life in sealed bag 12 months at &lt;40°C and &lt;90% relative humidity (RH)</li> <li>After this hag is opened devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing (peak package body temp. 220°C) must be:</li> <li>Za Mounted within 72 hours at factory condition of ≤ 30°C/60%RH or 2b.Stored at ≤20% RH.</li> <li>Devices require baking before mounting if:</li> <li>Humidity Indicator Card is &gt;20% when read at 23°C ± 5°C or 2a or 2b is not met.</li> <li>If baking is required, devices may be haked for:</li> <li>192 hours at 60.5°C and &lt;5%RH (dry air/nitrogen) or 96 hours at 60.5°C and &lt;5%RH (dry air/nitrogen) or 24 hours at 60.5°C and &lt;5%RH [To reall device containers or 24 hours at 50.5°C and &lt;5%RH [To reall device containers or 24 hours at 60.5°C and &lt;5%RH [To reall device containers or 24 hours at 60.5°C and &lt;5%RH [To reall device containers or 26 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 16 hours at 60.5°C and &lt;5%RH [To reall device containers or 17 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To reall device containers or 18 hours at 60.5°C and &lt;5%RH [To</li></ol>		ntains 🖌
vapor-phase reflow, or equivalent processing (peak package body temp. 220°C) must be: 2a Mounted within 72 hours at factory condition of ≤30°C/60%RH or 2b.Stored at ≤20% RH. 3. Devices require baking before mounting if: Humidity Indicator Card is >20% when read at 23°C ± 5°C or 2a or 2b is not met. 4. If baking is required, devices may be baked for: 192 hours at 40°C + 5°C/0°C and <5%RH (dry air/nitrogen) or 96 hours at 60.5°C and <5%RH (dry air/nitrogen) or 24 hours at 125±5°C Not suitable for reeks or tubes Bag Seal Date: (If blank, see bar code labet)	1. Shelf life in sealed bag 12 months at <40	PC and < 90% relative humidity (RH)
Humidity Indicator Card is >20% when read at 23°C ± 5°C or 2a or 2b is not met. 4. If baking is required, devices may be haked for: 192 hours at 40°C + 5°C/-0°C and <5%RH (dry air/nitrogen) or 96 hours at 025/Card <5%RH For all device containers or 24 hours at 125±5°C Not suitable for reeks or tubes Bag Seal Date: (If blank, see bar code labet)	vapor-phase reflow, or equivalent proce 220°C) must be: 2a.Mounted within 72 hours at factory co	ssing (peak package body temp.
192 hours at 40°C + 5°C/0°C and <5%RH (dry sir/nitrogen)	Humidity Indicator Card is >20% when	
96 hours at 6015°Cand <5%RH		
24 hours at 125±5°C Not suitable for reeks or tubes Bag Seal Date: (If blank, see bar code label)		
Bag Seal Date: (If blank, see bar code label)		
(If blank, see bar code label)		Not suitable for reels or tubes
NOCE, LE VEL GEIMEG BY BIA JEDIC SUBMARCHESDE2-ATT2	Note: LEVEL defined by EIA JE	DEC Standard JESD22-A112

Example of JESD22-A112 level 4 label



IR Receiver Modules for 3D Synchronization Signals

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#### ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.

#### VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.



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All product specifications and data are subject to change without notice.

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